

PJQ4670AP

100V Complementary Enhancement Mode MOSFET

Voltage 100/-100 V **Current** 10 / -7 A

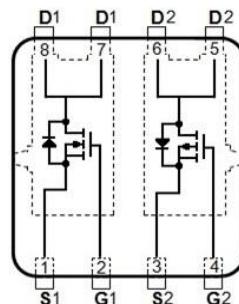
Features

- High switching speed
- Improved dv/dt capability
- Low Gate Charge
- Low reverse transfer capacitance
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 Standard

Mechanical Data

- Case: DFN3333B-8L Package
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.0271 grams

DFN3333B-8L



Maximum Ratings and Thermal Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	N-CH LIMIT	P-CH LIMIT	UNITS
Drain-Source Voltage	V_{DS}	100	-100	V
Gate-Source Voltage	V_{GS}	± 20		
Continuous Drain Current ^(Note 4)	I_D	10	-7	A
		6.5	-4.4	
Pulsed Drain Current ^(Note 1)	I_{DM}	17	-10	
Power Dissipation	P_D	30		W
		12		
Continuous Drain Current ^(Note 4)	I_D	2.7	-1.8	A
		2.1	-1.4	
Power Dissipation	P_D	1.9		W
		1.2		
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55-150		°C
Single Pulse Avalanche Current ^(Note 5,6)	I_{AS}	2.9	-3.6	A
Single Pulse Avalanche Energy ^(Note 5,6)	E_{AS}	3.9	6.1	mJ
Typical Thermal Resistance ^(Note 4)	Junction to Case	$R_{\theta JC}$	4.1	
	Junction to Ambient	$R_{\theta JA}$	65	

PJQ4670AP

N-CH Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	100	-	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1	1.6	2.5	
Drain-Source On-State Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=2\text{A}$	-	98	118	$\text{m}\Omega$
Drain-Source On-State Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=1\text{A}$	-	102	128	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Dynamic ^(Note 6)						
Total Gate Charge	Q_g	$V_{\text{DS}}=50\text{V}, I_{\text{D}}=2\text{A}, V_{\text{GS}}=10\text{V}$ ^(Note 2,3)	-	17.8	24	nC
Gate-Source Charge	Q_{gs}		-	3	-	
Gate-Drain Charge	Q_{gd}		-	2.7	-	
Input Capacitance	C_{iss}	$V_{\text{DS}}=50\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	-	863	1210	pF
Output Capacitance	C_{oss}		-	29	51	
Reverse Transfer Capacitance	C_{rss}		-	17	30	
Gate resistance	R_g	$f=1\text{MHz}$	-	2	-	Ω
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DS}}=50\text{V}, I_{\text{D}}=2\text{A}, V_{\text{GS}}=10\text{V}, R_{\text{G}}=3\Omega$ ^(Note 2,3)	-	5.6	-	ns
Turn-On Rise Time	t_r		-	2.6	-	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	21	-	
Turn-Off Fall Time	t_f		-	2.4	-	
Drain-Source Diode						
Diode Forward Current	I_s	$T_c=25^\circ\text{C}$	-	-	10	A
Pulsed Diode Forward Current	I_{SM}		-	-	17	
Diode Forward Voltage	V_{SD}	$I_s=2\text{A}, V_{\text{GS}}=0\text{V}$	-	0.8	1.3	V
Reverse Recovery Time	Tr_r	$V_{\text{DD}}=50\text{V}, V_{\text{GS}}=0\text{V}$ $I_s=10\text{A}, dI_s/dt=100\text{A}/\mu\text{s}$	-	28	-	ns
Reverse Recovery Charge	Q_{rr}		-	14	-	nC

PJQ4670AP

P-CH Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-100	-	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1	-1.8	-2.5	
Drain-Source On-State Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-2\text{A}$	-	246	295	$\text{m}\Omega$
Drain-Source On-State Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-1\text{A}$	-	263	329	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=-100\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Dynamic ^(Note 6)						
Total Gate Charge	Q_g	$V_{\text{DS}}=-50\text{V}, I_{\text{D}}=-2\text{A}$ $V_{\text{GS}}=-10\text{V}$ ^(Note 1,2)	-	19.7	26	nC
Gate-Source Charge	Q_{gs}		-	3.4	-	
Gate-Drain Charge	Q_{gd}		-	3	-	
Input Capacitance	C_{iss}	$V_{\text{DS}}=-50\text{V}, V_{\text{GS}}=0\text{V}$ $f=1\text{MHz}$	-	885	1240	pF
Output Capacitance	C_{oss}		-	31	55	
Reverse Transfer Capacitance	C_{rss}		-	21	37	
Gate resistance	R_g	$f=1\text{MHz}$	-	15	-	Ω
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DS}}=-50\text{V}, I_{\text{D}}=-2\text{A}$ $V_{\text{GS}}=-10\text{V}, R_G=3\Omega$ ^(Note 1,2)	-	5.8	-	ns
Turn-On Rise Time	t_r		-	3.5	-	
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	44	-	
Turn-Off Fall Time	t_f		-	16	-	
Drain-Source Diode						
Diode Forward Current	I_s	$T_c=25^\circ\text{C}$	-	-	-7	A
Pulsed Diode Forward Current	I_{SM}		-	-	-10	
Diode Forward Voltage	V_{SD}	$I_s=-2\text{A}, V_{\text{GS}}=0\text{V}$	-	-0.85	-1.3	V
Reverse Recovery Time	T_{rr}	$V_{\text{DD}}=-50\text{V}, V_{\text{GS}}=0\text{V}$ $I_s=-7\text{A}, dI_s/dt=100\text{A}/\mu\text{s}$	-	25	-	ns
Reverse Recovery Charge	Q_{rr}		-	27	-	nC

NOTES :

1. Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$.
2. Essentially independent of operating temperature typical characteristics.
3. The maximum current rating is package limited.
4. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz.square pad of copper.
5. E_{AS} of N-CH is calculated based on the condition of $L=1\text{mH}$, $I_{\text{AS}}=2.8\text{A}$, $V_{\text{DD}}=30\text{V}$, $V_{\text{GS}}=10\text{V}$. 100% test at $L=0.5\text{mH}$, $I_{\text{AS}}=2.9\text{A}$ in production.
6. E_{AS} of P-CH is calculated based on the condition of $L=1\text{mH}$, $I_{\text{AS}}=-3.5\text{A}$, $V_{\text{DD}}=-30\text{V}$, $V_{\text{GS}}=-10\text{V}$. 100% test at $L=0.5\text{mH}$, $I_{\text{AS}}=-3.6\text{A}$ in production.
7. Guaranteed by design, not subject to production testing.

PJQ4670AP

N-CH TYPICAL CHARACTERISTIC CURVES

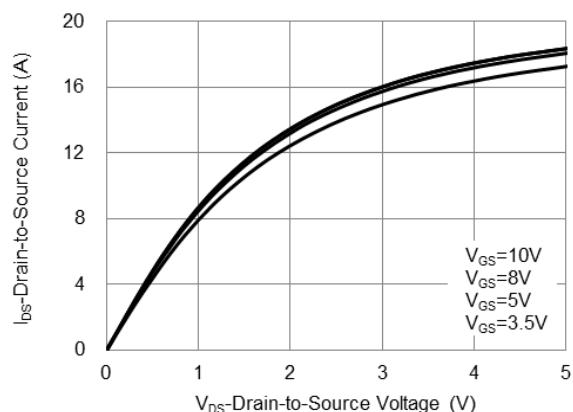


Fig.1 Output Characteristics

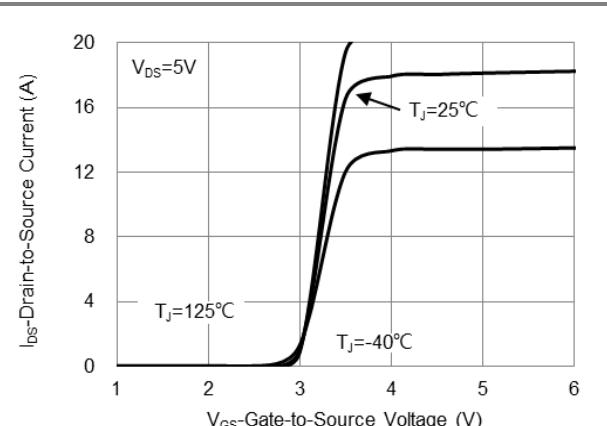


Fig.2 Transfer Characteristics

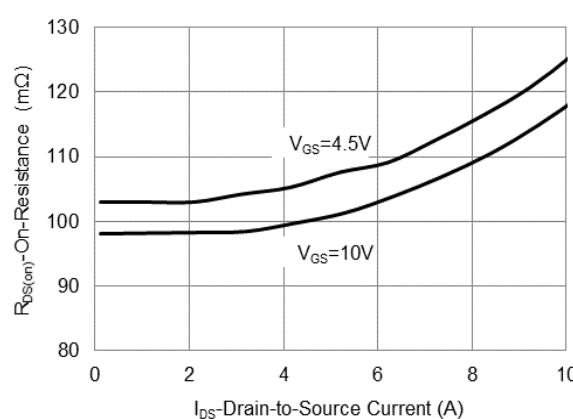


Fig.3 On-Resistance vs. Drain Current

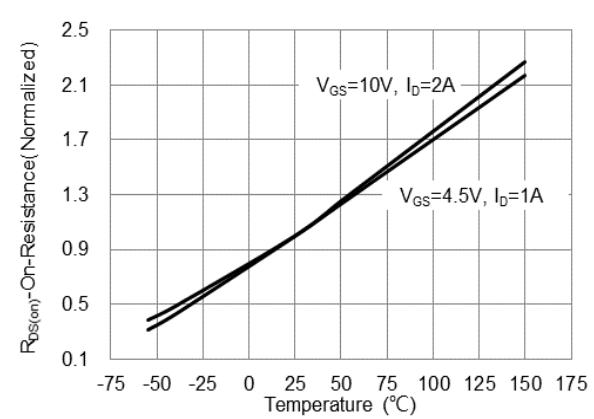


Fig.4 On-Resistance vs. Junction temperature

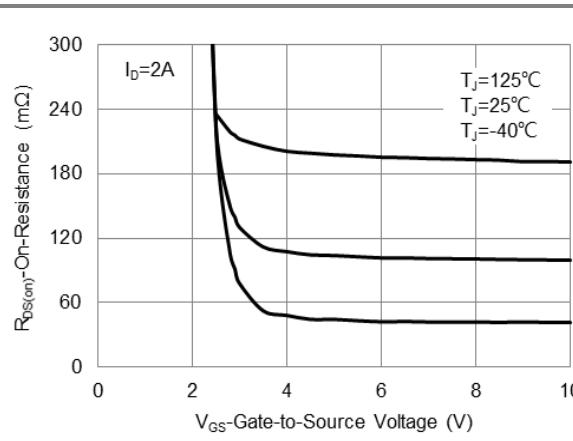


Fig.5 On-Resistance Variation with V_{GS}

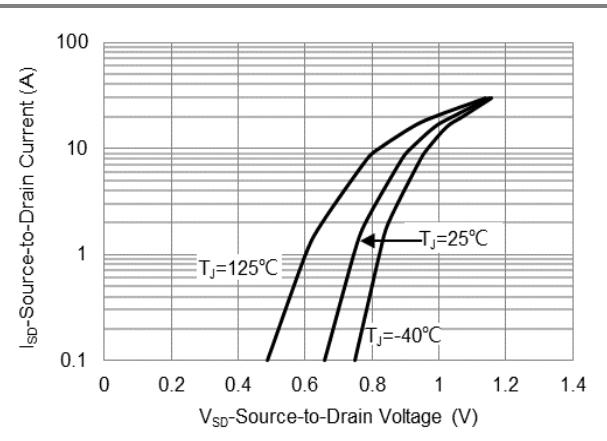
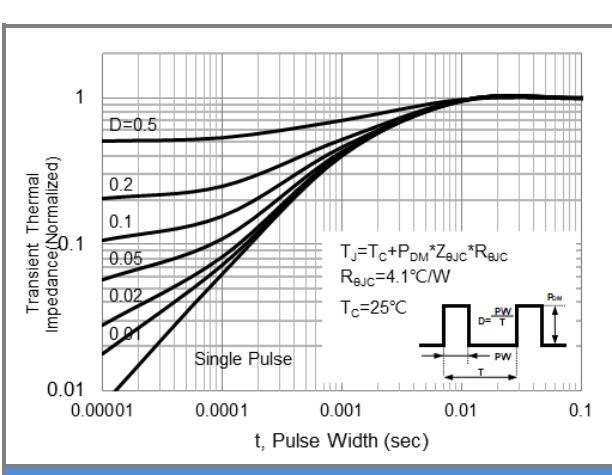
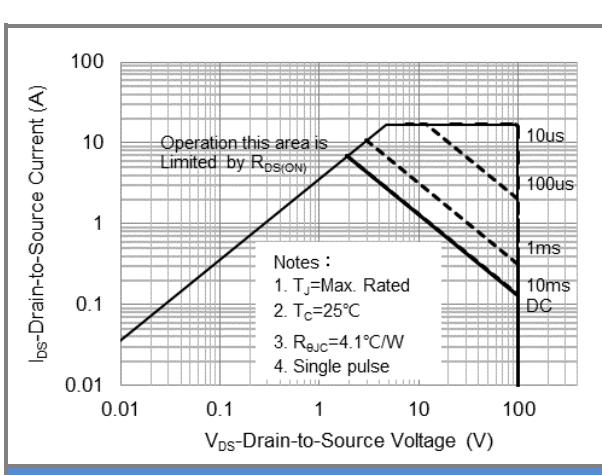
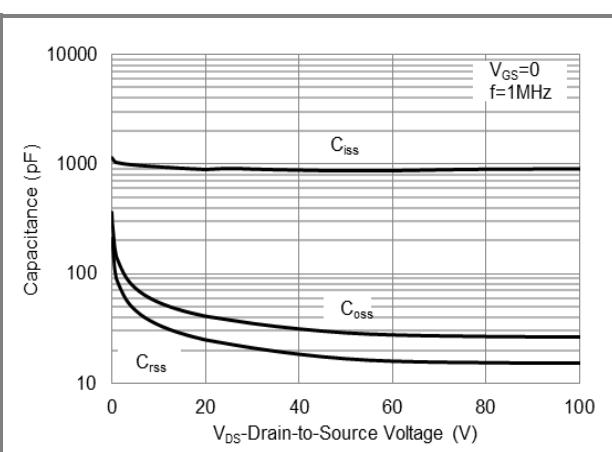
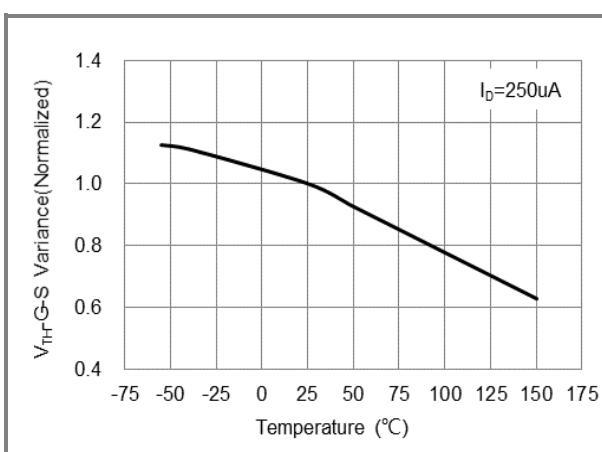
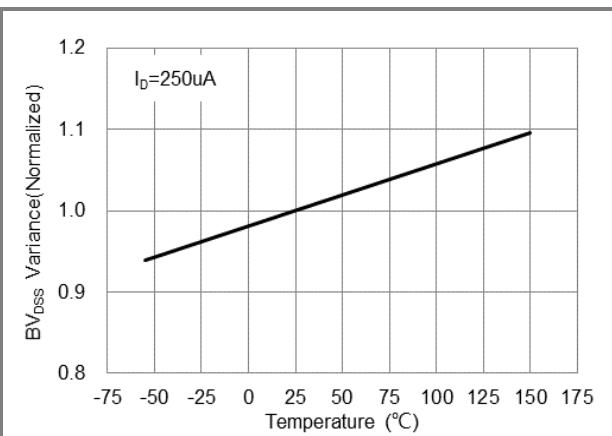
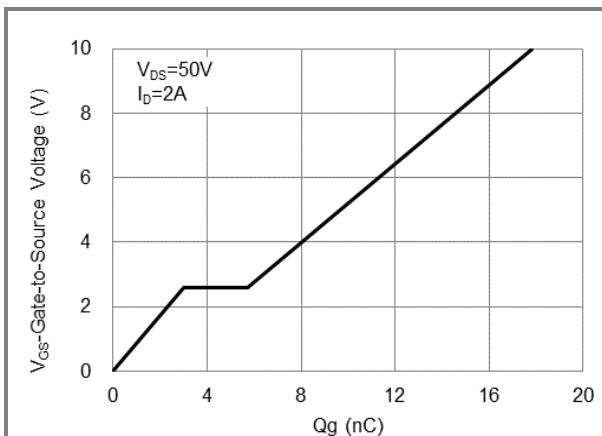


Fig.6 Source-Drain Diode Forward Voltage

PJQ4670AP

TYPICAL CHARACTERISTIC CURVES



PJQ4670AP

P-CH TYPICAL CHARACTERISTIC CURVES

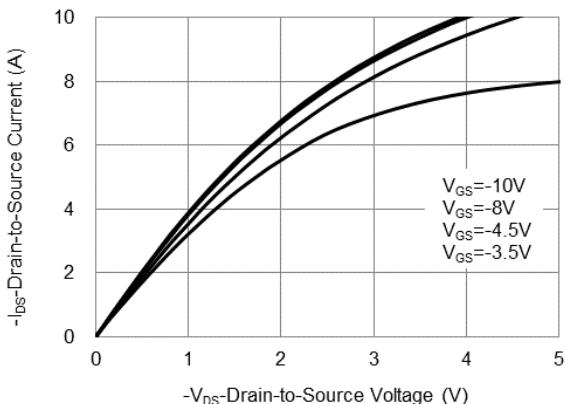


Fig.13 Output Characteristics

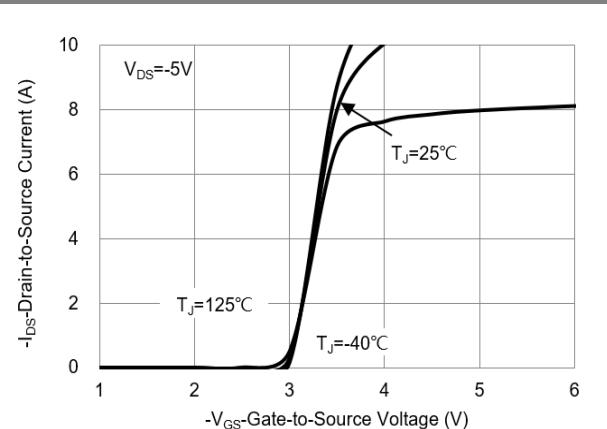


Fig.14 Transfer Characteristics

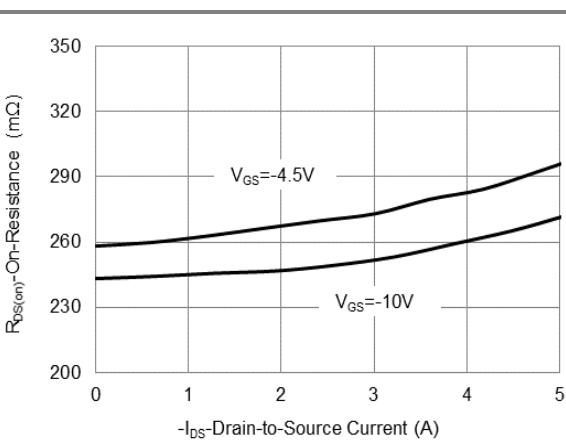


Fig.15 On-Resistance vs. Drain Current

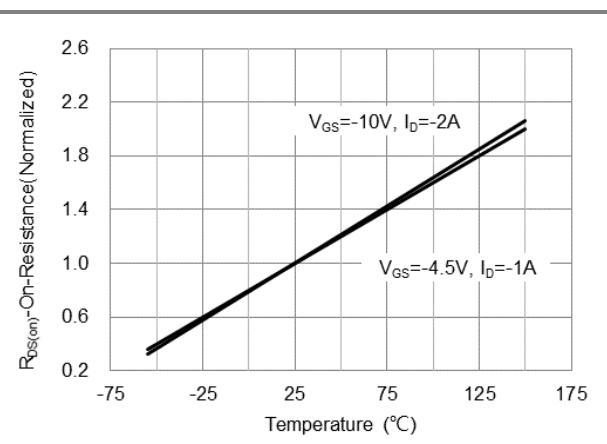


Fig.16 On-Resistance vs. Junction temperature

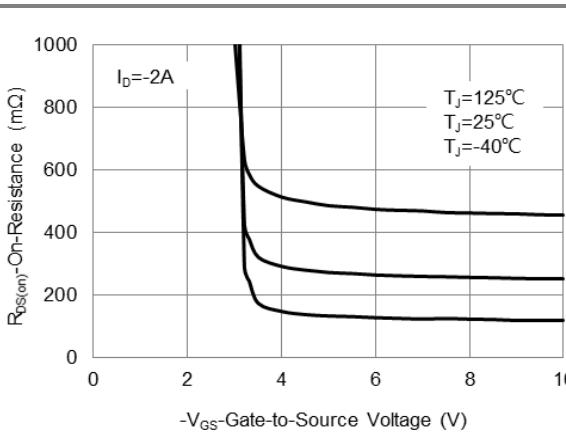


Fig.17 On-Resistance Variation with V_{GS}

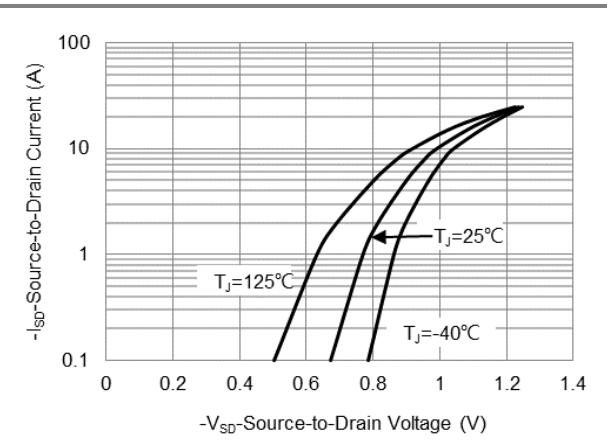


Fig.18 Source-Drain Diode Forward Voltage

PJQ4670AP

TYPICAL CHARACTERISTIC CURVES

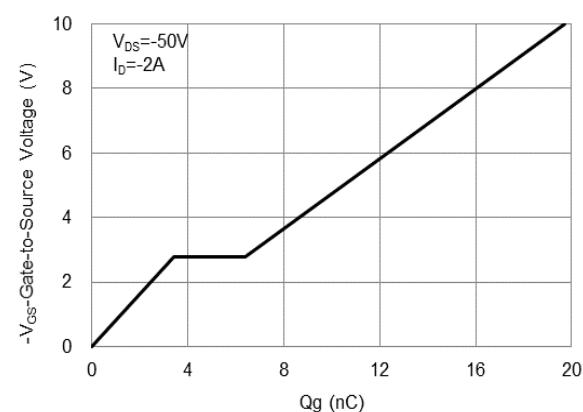


Fig.19 Gate-Charge Characteristics

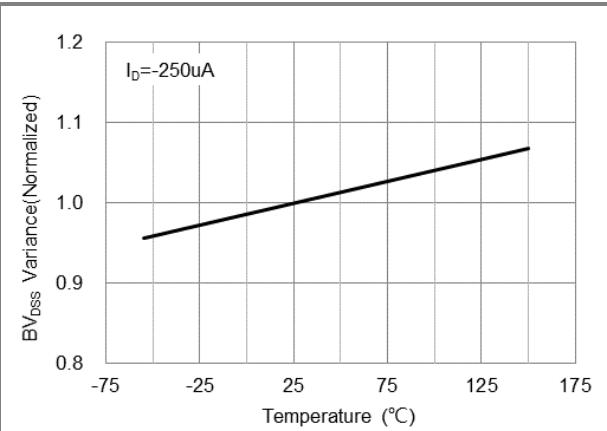


Fig.20 Breakdown Voltage Variation vs. Temperature

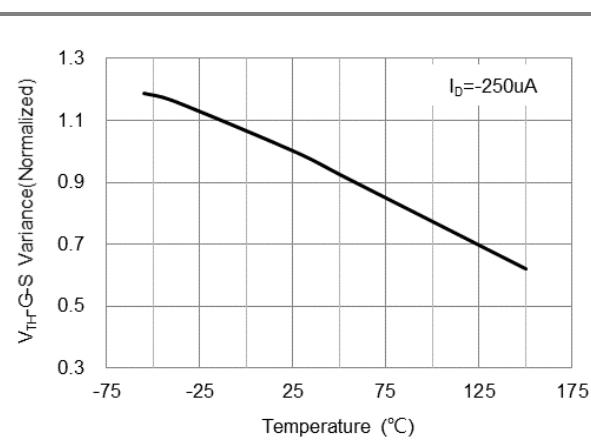


Fig.21 Threshold Voltage Variation with Temperature

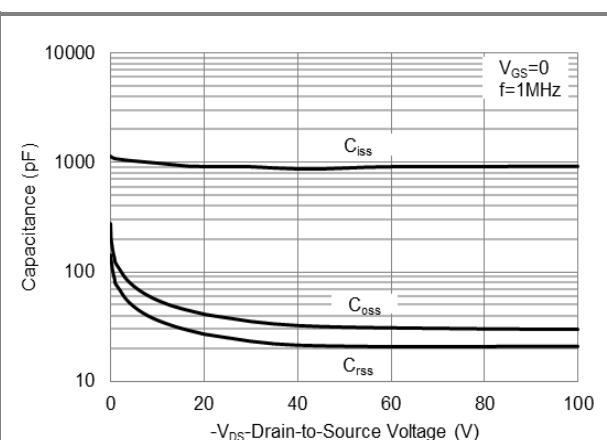


Fig.22 Capacitance vs. Drain-Source Voltage

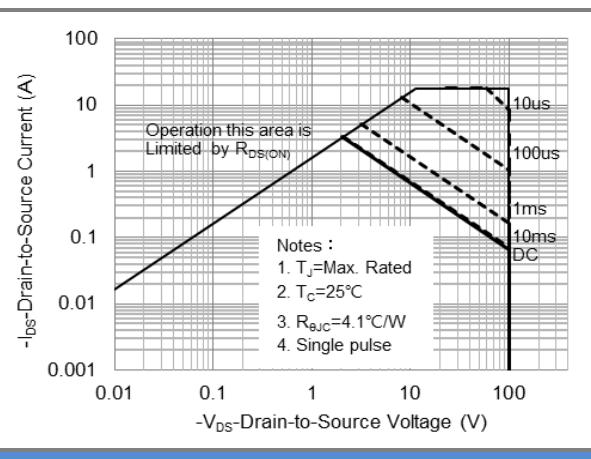


Fig.23 Maximum Safe Operating Area

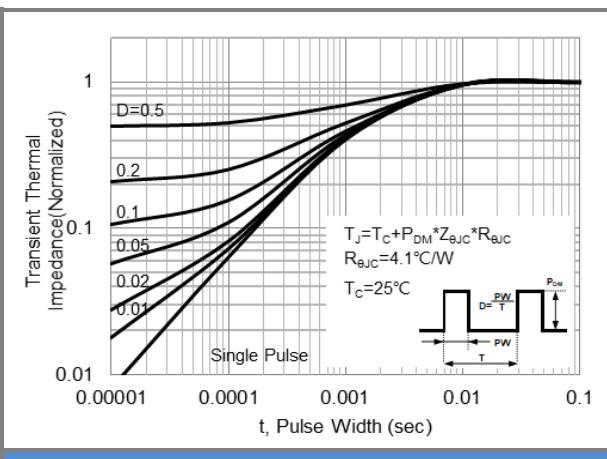


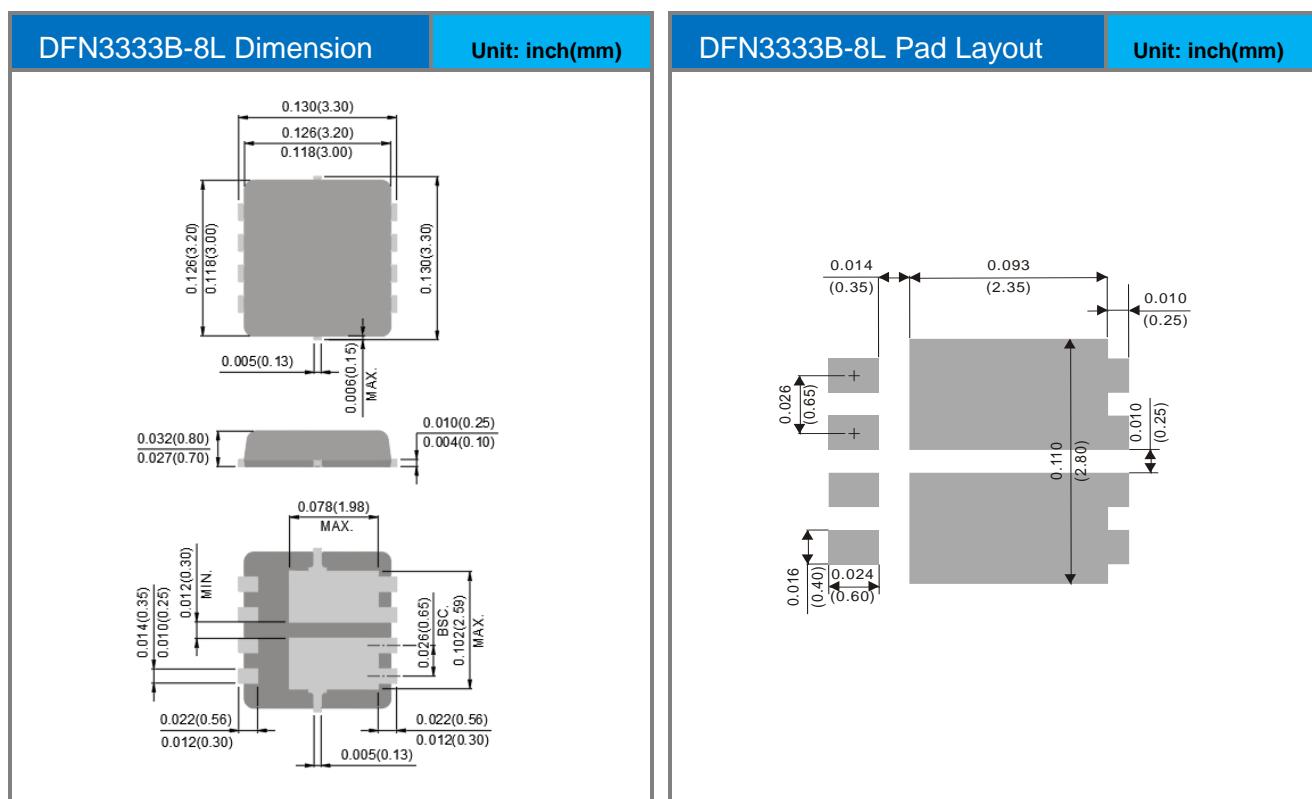
Fig.24 Normalized Transient Thermal Impedance

PJQ4670AP

Product and Packing Information

Part No.	Package Type	Packing Type	Marking
PJQ4670AP	DFN3333B-8L	5K pcs / 13" reel	670A

Packaging Information & Mounting Pad Layout



PJQ4670AP

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